



Material Content Data Sheet



Sales Product Name		BSZ12DN20NS3 G		Issued		20. July 2018		
MA#		MA000862672		Weight*		39.89 mg		
Package		PG-TSDSON-8-2						
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.374	3.44	3.44	34442	34442
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53	
	non noble metal	zinc	7440-66-6	0.008	0.02		210	
	non noble metal	iron	7439-89-6	0.168	0.42		4203	
wire	non noble metal	copper	7440-50-8	6.808	17.07	17.52	170652	175118
	non noble metal	copper	7440-50-8	0.049	0.12	0.12	1222	1222
	organic material	carbon black	1333-86-4	0.037	0.09		939	
encapsulation	plastics	epoxy resin	-	1.929	4.84		48359	
	inorganic material	silicondioxide	60676-86-0	16.763	42.01	46.94	420208	469506
leadfinish	non noble metal	tin	7440-31-5	0.387	0.97	0.97	9705	9705
plating	noble metal	silver	7440-22-4	0.963	2.41	2.41	24130	24130
solder	noble metal	silver	7440-22-4	0.038	0.10		955	
	non noble metal	tin	7440-31-5	0.030	0.08		764	
	non noble metal	lead	7439-92-1	1.455	3.65	3.83	36482	38201
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.086	0.22		2162	
	non noble metal	copper	7440-50-8	3.501	8.78	9.01	87766	90063
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47	
	non noble metal	zinc	7440-66-6	0.008	0.02		189	
	non noble metal	iron	7439-89-6	0.151	0.38		3783	
	non noble metal	copper	7440-50-8	6.127	15.36	15.76	153594	157613
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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